

# **RGP10A - RGP10M**

### **Features**

- 1.0 ampere operation at  $T_A = 55 \,^{\circ}\text{C}$ with no thermal runaway.
- · High temperature metallurgically bonded construction.
- Glass passivated cavity-free junction.
- Typical I<sub>R</sub> less than 1μA.
- · Fast switching for high efficiency.



# Fast Rectifiers (Glass Passivated)

# Absolute Maximum Ratings\* T<sub>A</sub> = 25 ℃ unless otherwise noted

Symbol	Parameter	Value			Units				
		10A	10B	10D	10G	10J	10K	10M	
$V_{RRM}$	Maximum Repetitive Reverse Voltage	50	100	200	400	600	800	1000	V
I <sub>F(AV)</sub>	Average Rectified Forward Current, .375 " lead length @ T <sub>L</sub> = 55°C	1.0			Α				
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave				Α				
T <sub>stg</sub>	Storage Temperature Range		-65 to +175						
T <sub>J</sub>	Operating Junction Temperature -65 to +175			°C					

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

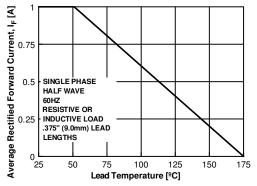
### **Thermal Characteristics**

Symbol	Parameter	Value	Units
$P_{D}$	Power Dissipation	3.0	W
R <sub>eJA</sub>	Thermal Resistance, Junction to Ambient	50	°C/W

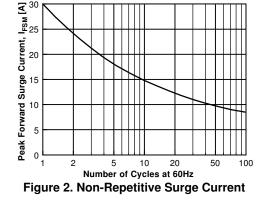
#### **Electrical Characteristics** T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parameter	Device					Units		
		10A	10B	10D	10G	10J	10K	10M	
$V_{F}$	Forward Voltage @ 1.0 A	1.3			V				
t <sub>rr</sub>	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$	150			250	500		ns	
I <sub>R</sub>	Reverse Current @ rated $V_R$ $T_A = 25^{\circ}C$ $T_A = 150^{\circ}C$	5.0 200			μ <b>Α</b> μ <b>Α</b>				
Ст	Total Capacitance V <sub>R</sub> = 4.0 V, f = 1.0 MHz	15			pF				

## **Typical Characteristics**



**Figure 1. Forward Current Derating Curve** 



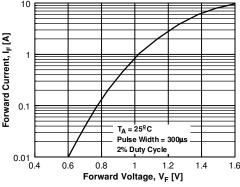


Figure 3. Forward Voltage Characteristics

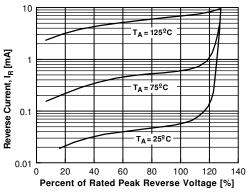


Figure 4. Reverse Current vs Reverse Voltage

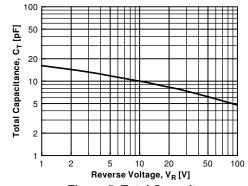
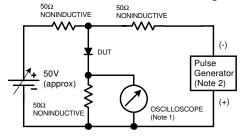
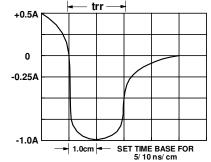


Figure 5. Total Capacitance





**Reverse Recovery Time Characterstic and Test Circuit Diagram** 

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Rev. H4